

Chunqing Wang

List of Publications by Year in descending order

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327
papers

4,005
citations

126907

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197818

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g-index

331
all docs

331
docs citations

331
times ranked

2577
citing authors

#	ARTICLE	IF	CITATIONS
1	Growth behavior of Cu/Al intermetallic compounds and cracks in copper ball bonds during isothermal aging. <i>Microelectronics Reliability</i> , 2008, 48, 416-424.	1.7	211
2	Rapid pressureless low-temperature sintering of Ag nanoparticles for high-power density electronic packaging. <i>Scripta Materialia</i> , 2013, 69, 789-792.	5.2	146
3	Ni@CeO ₂ composite cathode material for hydrogen evolution reaction in alkaline electrolyte. <i>International Journal of Hydrogen Energy</i> , 2012, 37, 13921-13932.	7.1	94
4	Formation mechanism and orientation of Cu ₃ Sn grains in Cu-Sn intermetallic compound joints. <i>Materials Letters</i> , 2013, 110, 137-140.	2.6	74
5	Fabrication of interconnects using pressureless low temperature sintered Ag nanoparticles. <i>Materials Letters</i> , 2012, 85, 61-63.	2.6	70
6	Multiferroic properties of La and Mn co-doped BiFeO ₃ nanofibers by sol-gel and electrospinning technique. <i>Materials Letters</i> , 2013, 90, 45-48.	2.6	70
7	Rapid formation of Cu/Cu ₃ Sn/Cu joints using ultrasonic bonding process at ambient temperature. <i>Applied Physics Letters</i> , 2013, 102, .	3.3	68
8	Influence of aging treatment on deformation behavior of 96.5Sn3.5Ag lead-free solder alloy during in situ tensile tests. <i>Journal of Alloys and Compounds</i> , 2007, 428, 274-285.	5.5	67
9	Relationship between morphologies and orientations of Cu ₆ Sn ₅ grains in Sn _{3.0} Ag _{0.5} Cu solder joints on different Cu pads. <i>Materials Characterization</i> , 2014, 88, 58-68.	4.4	63
10	Interfacial reactions of eutectic Sn _{3.5} Ag and pure tin solders with Cu substrates during liquid-state soldering. <i>Intermetallics</i> , 2012, 25, 86-94.	3.9	57
11	Sintering mechanism of the Cu-Ag core-shell nanoparticle paste at low temperature in ambient air. <i>RSC Advances</i> , 2016, 6, 91783-91790.	3.6	56
12	Recent Progress in Ohmic Contacts to Silicon Carbide for High-Temperature Applications. <i>Journal of Electronic Materials</i> , 2016, 45, 267-284.	2.2	56
13	Nanometer-Scale Heterogeneous Interfacial Sapphire Wafer Bonding for Enabling Plasmonic-Enhanced Nanofluidic Mid-Infrared Spectroscopy. <i>ACS Nano</i> , 2020, 14, 12159-12172.	14.6	54
14	Mechanisms for low-temperature direct bonding of Si/Si and quartz/quartz via VUV/O ₃ activation. <i>RSC Advances</i> , 2018, 8, 11528-11535.	3.6	52
15	Effects of bump size on deformation and fracture behavior of Sn _{3.0} Ag _{0.5} Cu/Cu solder joints during shear testing. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2011, 529, 468-478.	5.6	51
16	Ultrarapid formation of homogeneous Cu ₆ Sn ₅ and Cu ₃ Sn intermetallic compound joints at room temperature using ultrasonic waves. <i>Ultrasonics Sonochemistry</i> , 2014, 21, 924-929.	8.2	51
17	Microstructures, corrosion and mechanical properties of as-cast Mg-Zn-Y (Gd) alloys. <i>Transactions of Nonferrous Metals Society of China</i> , 2015, 25, 2172-2180.	4.2	51
18	Extremely fast formation of Cu Sn intermetallic compounds in Cu/Sn/Cu system via a micro-resistance spot welding process. <i>Journal of Alloys and Compounds</i> , 2016, 687, 667-673.	5.5	50

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19	Aging effects on fracture behavior of 63Sn37Pb eutectic solder during tensile tests under the SEM. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2004, 384, 314-323.	5.6	50
20	Low Temperature Sintering Cu ₆ Sn ₅ Nanoparticles for Superplastic and Superuniform High Temperature Circuit Interconnections. <i>Small</i> , 2015, 11, 4097-4103.	10.0	48
21	Silk fibroin film-coated MgZnCa alloy with enhanced in vitro and in vivo performance prepared using surface activation. <i>Acta Biomaterialia</i> , 2019, 91, 99-111.	8.3	48
22	Investigation of ultrasonic copper wire wedge bonding on Au/Ni plated Cu substrates at ambient temperature. <i>Journal of Materials Processing Technology</i> , 2008, 208, 179-186.	6.3	47
23	Mechanical properties and fracture mechanisms of Sn-3.0Ag-0.5Cu solder alloys and joints at cryogenic temperatures. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2017, 684, 697-705.	5.6	42
24	Glass-on-LiNbO ₃ heterostructure formed via a two-step plasma activated low-temperature direct bonding method. <i>Applied Surface Science</i> , 2018, 459, 621-629.	6.1	42
25	Electrochemical synthesis of NiS/CeO ₂ composite electrodes for hydrogen evolution reaction. <i>Journal of Power Sources</i> , 2013, 230, 10-14.	7.8	41
26	Electronic structure mechanism for the wettability of Sn-based solder alloys. <i>Journal of Electronic Materials</i> , 2002, 31, 185-190.	2.2	40
27	Determination of the Elastic Properties of Cu ₃ Sn Through First-Principles Calculations. <i>Journal of Electronic Materials</i> , 2008, 37, 477-482.	2.2	38
28	Finite element modeling of electron beam welding of a large complex Al alloy structure by parallel computations. <i>Journal of Materials Processing Technology</i> , 2008, 199, 41-48.	6.3	38
29	Electrodeposition fabrication of Cu@Ni core shell nanowire network for highly stable transparent conductive films. <i>Chemical Engineering Journal</i> , 2020, 390, 124495.	12.7	38
30	Microstructural study of copper free air balls in thermosonic wire bonding. <i>Microelectronic Engineering</i> , 2008, 85, 1815-1819.	2.4	36
31	Intermetallic compounds formation at interface between PBGA solder ball and Au/Ni/Cu/BT PCB substrate after laser reflow processes. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , 2002, 95, 254-262.	3.5	35
32	Effect of electric current on grain orientation and mechanical properties of Cu-Sn intermetallic compounds joints. <i>Journal of Alloys and Compounds</i> , 2018, 753, 203-211.	5.5	35
33	Effect of electronic flame off parameters on copper bonding wire: Free-air ball deformability, heat affected zone length, heat affected zone breaking force. <i>Microelectronic Engineering</i> , 2009, 86, 2094-2103.	2.4	34
34	Ultrafast formation of unidirectional and reliable Cu ₃ Sn-based intermetallic joints assisted by electric current. <i>Intermetallics</i> , 2017, 80, 26-32.	3.9	34
35	Effect of Cu grain size on the voiding propensity at the interface of SnAgCu/Cu solder joints. <i>Materials Letters</i> , 2015, 144, 97-99.	2.6	33
36	Microstructure evolution and thermostability of bondline based on Cu@Sn core-shell structured microparticles under high-temperature conditions. <i>Materials and Design</i> , 2017, 131, 196-203.	7.0	33

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37	Recent Progress in Rapid Sintering of Nanosilver for Electronics Applications. <i>Micromachines</i> , 2018, 9, 346.	2.9	33
38	Direct bonding of silicon and quartz glass using VUV/O ₃ activation and a multistep low-temperature annealing process. <i>Applied Surface Science</i> , 2018, 453, 416-422.	6.1	33
39	Reliability and failure analysis of fine copper wire bonds encapsulated with commercial epoxy molding compound. <i>Microelectronics Reliability</i> , 2011, 51, 157-165.	1.7	30
40	The influence of strengthening and recrystallization to the cracking behavior of Ni, Sb, Bi alloyed SnAgCu solder during thermal cycling. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 652, 264-270.	5.6	30
41	Enhanced shear strength of Cu-Sn intermetallic interconnects with interlocking dendrites under fluxless electric current-assisted bonding process. <i>Journal of Materials Science</i> , 2017, 52, 1943-1954.	3.7	30
42	Room-temperature direct bonding of silicon and quartz glass wafers. <i>Applied Physics Letters</i> , 2017, 110, .	3.3	29
43	Chemical and thermal robust tri-layer rGO/Ag NWs/GO composite film for wearable heaters. <i>Composites Science and Technology</i> , 2019, 174, 76-83.	7.8	29
44	Low-temperature-solderable intermetallic nanoparticles for 3D printable flexible electronics. <i>Acta Materialia</i> , 2019, 162, 163-175.	7.9	29
45	Investigation on Sn grain number and crystal orientation in the Sn-Ag-Cu/Cu solder joints of different sizes. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 1174-1180.	2.2	28
46	Electromigration-induced intermetallic growth and voids formation in symmetrical Cu/Sn/Cu and Cu/Intermetallic compounds (IMCs)/Cu joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 2674-2681.	2.2	27
47	Cohesively enhanced electrical conductivity and thermal stability of silver nanowire networks by nickel ion bridge joining. <i>Scientific Reports</i> , 2018, 8, 5260.	3.3	27
48	High-efficiency extraction synthesis for high-purity copper nanowires and their applications in flexible transparent electrodes. <i>Nano Materials Science</i> , 2020, 2, 164-171.	8.8	27
49	Interdiffusion of Al-Ni system enhanced by ultrasonic vibration at ambient temperature. <i>Ultrasonics</i> , 2006, 45, 61-65.	3.9	26
50	Room-Temperature Direct Bonding Using Fluorine Containing Plasma Activation. <i>Journal of the Electrochemical Society</i> , 2011, 158, H525.	2.9	26
51	Morphologies and grain orientations of Cu-Sn intermetallic compounds in Sn _{3.0} Ag _{0.5} Cu/Cu solder joints. <i>Materials Letters</i> , 2012, 86, 157-160.	2.6	26
52	Fabrication of SiC/Si, SiC/SiO ₂ , and SiC/glass heterostructures via VUV/O ₃ activated direct bonding at low temperature. <i>Ceramics International</i> , 2019, 45, 4094-4098.	4.8	26
53	Bonding wire characterization using automatic deformability measurement. <i>Microelectronic Engineering</i> , 2008, 85, 1795-1803.	2.4	25
54	A Comparative Study: Void Formation in Silicon Wafer Direct Bonding by Oxygen Plasma Activation with and without Fluorine. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P7-P13.	1.8	25

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55	Growth kinetics of Cu ₆ Sn ₅ intermetallic compound in Cu-liquid Sn interfacial reaction enhanced by electric current. <i>Scientific Reports</i> , 2018, 8, 1775.	3.3	25
56	Evolution of the bond interface during ultrasonic Al-Si wire wedge bonding process. <i>Journal of Materials Processing Technology</i> , 2007, 182, 202-206.	6.3	24
57	Nano features of Al/Au ultrasonic bond interface observed by high resolution transmission electron microscopy. <i>Materials Characterization</i> , 2008, 59, 1419-1424.	4.4	24
58	Bonding mechanism of ultrasonic wedge bonding of copper wire on Au/Ni/Cu substrate. <i>Transactions of Nonferrous Metals Society of China</i> , 2008, 18, 132-137.	4.2	24
59	Progress in wafer bonding technology towards MEMS, high-power electronics, optoelectronics, and optofluidics. <i>International Journal of Optomechatronics</i> , 2020, 14, 94-118.	6.6	24
60	Investigation of fluorine containing plasma activation for room-temperature bonding of Si-based materials. <i>Microelectronics Reliability</i> , 2012, 52, 347-351.	1.7	23
61	Fabrication and characterization of silk fibroin coating on APTES pretreated Mg-Zn-Ca alloy. <i>Materials Science and Engineering C</i> , 2020, 110, 110742.	7.3	23
62	TEM observation of interfacial compounds of SnAgCu/ENIG solder bump after laser soldering and subsequent hot air reflows. <i>Materials Letters</i> , 2016, 163, 254-257.	2.6	22
63	A novel cobalt-free CO ₂ -stable perovskite-type oxygen permeable membrane. <i>Journal of Membrane Science</i> , 2019, 573, 504-510.	8.2	22
64	An integrated system for prediction and analysis of solder interconnection shapes. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2000, 23, 87-92.	1.4	21
65	Effects of ultrasonic irradiation and cooling rate on the solidification microstructure of Sn-3.0Ag-0.5Cu alloy. <i>Journal of Materials Processing Technology</i> , 2014, 214, 13-20.	6.3	21
66	Phase transformation and fracture behavior of Cu/In/Cu joints formed by solid-liquid interdiffusion bonding. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 4170-4178.	2.2	21
67	Ultrafine-Grain and Isotropic Cu/SAC305/Cu Solder Interconnects Fabricated by High-Intensity Ultrasound-Assisted Solidification. <i>Journal of Electronic Materials</i> , 2014, 43, 2467-2478.	2.2	21
68	Recycled low-temperature direct bonding of Si/glass and glass/glass chips for detachable micro/nanofluidic devices. <i>Journal of Materials Science and Technology</i> , 2020, 46, 156-167.	10.7	21
69	Low-Temperature Co-hydroxylated Cu/SiO ₂ Hybrid Bonding Strategy for a Memory-Centric Chip Architecture. <i>ACS Applied Materials & Interfaces</i> , 2021, 13, 38866-38876.	8.0	21
70	Effect of solidification on solder bump formation in solder jet process: Simulation and experiment. <i>Transactions of Nonferrous Metals Society of China</i> , 2008, 18, 1201-1208.	4.2	20
71	Effect of Au-Sn IMCs formation and morphologies on shear properties of laser reflowed micro-solder joints. <i>Soldering and Surface Mount Technology</i> , 2015, 27, 45-51.	1.5	20
72	A facile method for direct bonding of single-crystalline SiC to Si, SiO ₂ , and glass using VUV irradiation. <i>Applied Surface Science</i> , 2019, 471, 196-204.	6.1	20

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73	Aging effects on fracture behavior of 63Sn37Pb eutectic solder during tensile tests under the SEM. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2004, 384, 314-323.	5.6	19
74	In situ quantitative study of microstructural evolution at the interface of Sn3.0Ag0.5Cu/Cu solder joint during solid state aging. <i>Journal of Alloys and Compounds</i> , 2015, 634, 94-98.	5.5	19
75	Direct Homo/Heterogeneous Bonding of Silicon and Glass Using Vacuum Ultraviolet Irradiation in Air. <i>Journal of the Electrochemical Society</i> , 2018, 165, H3093-H3098.	2.9	19
76	Maximum shear stress-controlled uniaxial tensile deformation and fracture mechanisms and constitutive relations of Sn-Pb eutectic alloy at cryogenic temperatures. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2021, 819, 141523.	5.6	19
77	Effect of intermetallic compounds on fracture behaviors of Sn3.0Ag0.5Cu lead-free solder joints during in situ tensile test. <i>Journal of Materials Science: Materials in Electronics</i> , 2012, 23, 136-147.	2.2	18
78	Cu nanoparticles of low polydispersity synthesized by a double-template method and their stability. <i>Colloid and Polymer Science</i> , 2014, 292, 715-722.	2.1	18
79	Comparison of interface evolution of ultrasonic aluminum and gold wire wedge bonds during thermal aging. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2007, 447, 111-118.	5.6	17
80	Cross-Interaction of Interfacial Reactions in Ni (Au/Ni/Cu)-SnAg-Cu Solder Joints during Reflow Soldering and Thermal Aging. <i>Journal of Electronic Materials</i> , 2007, 36, 26-32.	2.2	17
81	Mechanical properties and microstructures of hybrid ultrasonic resistance brazing of WC-Co/BeCu. <i>Journal of Materials Processing Technology</i> , 2012, 212, 1885-1891.	6.3	17
82	Degradation behaviors of micro ball grid array (µBGA) solder joints under the coupled effects of electromigration and thermal stress. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 11583-11592.	2.2	17
83	Facile synthesis of Cu-Ag hybrid nanowires with strong surface-enhanced Raman scattering sensitivity. <i>CrystEngComm</i> , 2016, 18, 1200-1206.	2.6	17
84	One-Step Fabrication of 3D Nanohierarchical Nickel Nanomace Array To Sinter with Silver NPs and the Interfacial Analysis. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 4798-4807.	8.0	17
85	Mechanisms for Room-Temperature Fluorine Containing Plasma Activated Bonding. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P373-P378.	1.8	17
86	Thermomechanical behaviour of PBGA package during laser and hot air reflow soldering. <i>Modelling and Simulation in Materials Science and Engineering</i> , 2004, 12, 235-243.	2.0	16
87	The effects of pulsed Nd:YAG laser irradiation on surface energy of copper. <i>Applied Surface Science</i> , 2006, 252, 4257-4263.	6.1	16
88	Determination of the Elastic Properties of Au5Sn and AuSn from Ab Initio Calculations. <i>Journal of Electronic Materials</i> , 2008, 37, 968-974.	2.2	16
89	Study of electroless Sn-coated Cu microparticles and their application as a high temperature thermal interface material. <i>Surface and Coatings Technology</i> , 2017, 319, 230-240.	4.8	16
90	High-Efficient Vacuum Ultraviolet-Ozone Assist-Deposited Polydopamine for Poly(lactic-co-glycolic acid)-Coated Pure Zn toward Biodegradable Cardiovascular Stent Applications. <i>ACS Applied Materials & Interfaces</i> , 2022, 14, 3536-3550.	8.0	16

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91	Synthesis of Co-doped barium strontium titanate nanofibers by sol-gel/electrospinning process. <i>Materials Letters</i> , 2012, 75, 207-210.	2.6	15
92	The role of chloride ions in rapid synthesis of ultra-long silver nanowires for flexible electrodes. <i>Materials Research Express</i> , 2016, 3, 075007.	1.6	15
93	Superior rate and long-lived performance of few-layered black phosphorus-based hybrid anode for lithium-ion batteries. <i>Electrochimica Acta</i> , 2022, 403, 139697.	5.2	15
94	Study of copper free air ball in thermosonic copper ball bonding. , 0, , .		14
95	Fabrication of multiferroic Ba _{0.7} Sr _{0.3} TiO ₃ ∕Ni _{0.8} Zn _{0.2} Fe ₂ O ₄ composite nanofibers by electrospinning. <i>Materials Letters</i> , 2013, 91, 55-58.	2.6	14
96	Low-temperature wafer direct bonding of silicon and quartz glass by a two-step wet chemical surface cleaning. <i>Japanese Journal of Applied Physics</i> , 2018, 57, 02BD02.	1.5	14
97	Effect of Diamond Additions on Wettability and Distribution of SnAgCu Composite Solder. <i>Journal of Materials Science and Technology</i> , 2012, 28, 661-665.	10.7	13
98	Scanning electron microscope in-situ investigation of fracture behavior in 96.5Sn3.5Ag lead-free solder. <i>Journal of Electronic Materials</i> , 2005, 34, 1324-1335.	2.2	12
99	In situ TEM observation of microcrack nucleation and propagation in pure tin solder. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , 2006, 127, 62-69.	3.5	12
100	Synthesis of multiferroic Bi _{0.9} La _{0.1} Fe _{0.95} Mn _{0.05} O ₃ ∕Ba _{0.7} Sr _{0.3} TiO ₃ ∕Ni _{0.8} Zn _{0.2} Fe ₂ O ₄ nanotubes with one closed end using a template-assisted sol-gel process. <i>CrystEngComm</i> , 2013, 15, 2147.	2.6	12
101	The Investigation of Quality of Life in 87 Chinese Patients with Disorders of Sex Development. <i>BioMed Research International</i> , 2015, 2015, 1-6.	1.9	12
102	The Fabrication of Micro-Array Channels with the Ultrafine-Grained LZ91 Mg-Li Alloy by Micro-Embossing. <i>Micromachines</i> , 2018, 9, 55.	2.9	12
103	Low-temperature direct bonding of Si and quartz glass using the APTES modification. <i>Ceramics International</i> , 2019, 45, 16670-16675.	4.8	12
104	Rapid pressureless and low-temperature bonding of large-area power chips by sintering two-step activated Ag paste. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 6497-6505.	2.2	12
105	Evolution of deformation near the triple point of grain junctions in Sn-based solders during in situ tensile test. <i>Materials Letters</i> , 2005, 59, 697-700.	2.6	11
106	Fabrication of Cu ₆ Sn ₅ single-crystal layer for under-bump metallization in flip-chip packaging. <i>Intermetallics</i> , 2013, 42, 52-55.	3.9	11
107	Effect of the Silver Content of SnAgCu Solder on the Interfacial Reaction and on the Reliability of Angle Joints Fabricated by Laser-Jet Soldering. <i>Journal of Electronic Materials</i> , 2015, 44, 733-743.	2.2	11
108	One-Step Fabrication of Copper Nanopillar Array-Filled AAO Films by Pulse Electrodeposition for Anisotropic Thermal Conductive Interconnectors. <i>ACS Omega</i> , 2019, 4, 6092-6096.	3.5	11

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109	Oxidation and Au-Sn reaction of laser reflowed micro-solder joints protected by N ₂ or exposed to air atmosphere. Soldering and Surface Mount Technology, 2012, 24, 191-196.	1.5	10
110	Optimization and modeling for one-step synthesis process of Ag-Cu nano-particles using DOE methodology. Journal of Materials Science: Materials in Electronics, 2016, 27, 4265-4274.	2.2	10
111	Micro heat pipe device utilizing extended nanofluidics. RSC Advances, 2017, 7, 50591-50597.	3.6	10
112	Solderless bonding with nanoporous copper as interlayer for high-temperature applications. Microelectronics Reliability, 2018, 80, 198-204.	1.7	10
113	Communication-Ag NW Networks Enhanced by Ni Electroplating for Flexible Transparent Electrodes. Journal of the Electrochemical Society, 2018, 165, D328-D330.	2.9	10
114	Shear Deformation Behaviors of Sn _{3.5} Ag Lead-free Solder Samples. Journal of Materials Science and Technology, 2013, 29, 471-479.	10.7	9
115	Joining of Silver Nanowires by Femtosecond Laser Irradiation Method. Materials Transactions, 2015, 56, 981-983.	1.2	9
116	Computer simulation of three-dimensional castellated solder joint geometry in surface mount technology. Modelling and Simulation in Materials Science and Engineering, 1998, 6, 557-565.	2.0	8
117	Evolution of Cu/Al Intermetallic Compounds in the Copper Bump bonds during Aging Process. , 2007, , .		8
118	Effects of Solder Volume on Formation and Redeposition of Au-Containing Intermetallics in Ni/Au-SnAgCu-Ni(P) Solder Joints. Journal of Electronic Materials, 2007, 36, 33-39.	2.2	8
119	Mechanism of low temperature Cu-In Solid-Liquid Interdiffusion bonding in 3D package. , 2012, , .		8
120	Parallel-gap resistance welding between gold-plated silver interconnects and silver electrodes in germanium solar cells. , 2014, , .		8
121	Fabrication of Al ₂ O ₃ -Mullite-AlN Multiphase Ceramic Layer on W-Cu Substrates for Power Semiconductor Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 182-187.	2.5	8
122	Microstructures and Properties of As-Cast Mg ₉₂ Zn ₄ Y ₄ and Mg ₉₂ Zn ₄ Y ₃ Gd ₁ Alloys with LPSO Phase. Rare Metal Materials and Engineering, 2015, 44, 1617-1622.	0.8	8
123	Effects of temperature and dispersants on the phases and morphology of Ag-Cu nanoparticles. Journal of Materials Science: Materials in Electronics, 2016, 27, 10065-10069.	2.2	8
124	Low temperature nanojoining of silver-copper nanopaste as die attach material for high temperature packaging. Journal of Materials Science: Materials in Electronics, 2017, 28, 5446-5451.	2.2	8
125	Room-Temperature Direct Heterogeneous Bonding of Glass and Polystyrene Substrates. Journal of the Electrochemical Society, 2018, 165, B3091-B3097.	2.9	8
126	Communication-Defect-Free Direct Bonding for High-Performance Glass-On-LiNbO ₃ Devices. Journal of the Electrochemical Society, 2018, 165, B727-B729.	2.9	8

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127	VUV/O ₃ activated direct heterogeneous bonding towards high-performance LiNbO ₃ -based optical devices. <i>Applied Surface Science</i> , 2019, 495, 143576.	6.1	8
128	Dissimilatory iron reduction and potential methane production in Chagan Lake wetland soils with carbon addition. <i>Wetlands Ecology and Management</i> , 2021, 29, 369-379.	1.5	8
129	Interaction kinetics between PBGA solder balls and Au/Ni/Cu metallisation during laser reflow bumping. <i>Soldering and Surface Mount Technology</i> , 2003, 15, 17-21.	1.5	8
130	In situ measurement of bond resistance varying with process parameters during ultrasonic wedge bonding. <i>Journal of Materials Processing Technology</i> , 2009, 209, 139-144.	6.3	7
131	The effects of humidity and temperature aging test on flexible packaging LED module. , 2013, , .		7
132	Laser Sintering of Nano-Ag Particle Paste for High-Temperature Electronics Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017, 7, 1050-1057.	2.5	7
133	Nd:YAG laser surface treatment of copper to improve the wettability of Sn _{3.5} Ag solder on copper. <i>Surface and Coatings Technology</i> , 2005, 200, 2181-2186.	4.8	6
134	In-situ SEM observation on fracture behaviors of Sn-based solder alloys. <i>Journal of Materials Science</i> , 2005, 40, 1993-2001.	3.7	6
135	The effect of voids on thermal conductivity of solder joints. , 2012, , .		6
136	Formation of AuSn _x IMCs in Sn _{3.5} Ag _{0.75} Cu micro-solder joints fabricated by laser and hot air reflow processes. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 217-223.	2.2	6
137	Preparation and Sintering Properties of Ag ₂₇ Cu ₂ Sn Nanopaste as Die Attach Material. <i>Journal of Electronic Materials</i> , 2016, 45, 5436-5442.	2.2	6
138	Communicationâ€™ Fluorinated Plasma Treatments Using PTFE Substrates for Room-Temperature Silicon Wafer Direct Bonding. <i>ECS Journal of Solid State Science and Technology</i> , 2016, 5, P393-P395.	1.8	6
139	MoirÃ©-Based Alignment Using Centrosymmetric Grating Marks for High-Precision Wafer Bonding. <i>Micromachines</i> , 2019, 10, 339.	2.9	6
140	Unique buoyancy-force-based kinetics determination of beta to alpha phase transformation in bulk tin plates. <i>Materials and Design</i> , 2020, 190, 108550.	7.0	6
141	Low-temperature Cu/SiO ₂ hybrid bonding using a novel two-step cooperative surface activation. , 2021, , .		6
142	Interfacial Characterization and Bonding Mechanism of Ultrasonic Wedge Bonding. , 2006, , .		5
143	Three-dimensional modelling of solder droplet impact onto a groove. <i>Journal Physics D: Applied Physics</i> , 2008, 41, 245503.	2.8	5
144	Self-assembly of three-dimensional microstructures in MEMS via fluxless laser reflow soldering. , 2011, , .		5

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145	Surface-Tension-Driven Self-Assembly of 3-D Microcomponents by Using Laser Reflow Soldering and Wire Limiting Mechanisms. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 168-176.	2.5	5
146	Effects of Ba _{0.7} Sr _{0.3} TiO ₃ -based buffer layers and La/Mn doping on the crystallization behavior and multiferroic properties of BiFeO ₃ thin films. RSC Advances, 2014, 4, 55889-55896.	3.6	5
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